

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUC60N04S6L045H	**Issued**	15. May 2021
MA#	MA004441482		
Package	PG-TDSON-8-57	**Weight***	99.32 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.268	0.27	0.27	2693	2693
chip_2	inorganic material	silicon	7440-21-3	0.268	0.27	0.27	2693	2693
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		137	
	non noble metal	iron	7439-89-6	0.045	0.05		456	
	non noble metal	copper	7440-50-8	45.219	45.53	45.59	455269	455862
wire	noble metal	gold	7440-57-5	0.061	0.06	0.06	616	616
encapsulation	organic material	carbon black	1333-86-4	0.081	0.08		820	
	plastics	epoxy resin	-	6.433	6.48		64769	
	inorganic material	silicondioxide	60676-86-0	34.201	34.43	40.99	344342	409931
leadfinish	non noble metal	tin	7440-31-5	0.512	0.52	0.52	5158	5158
plating	noble metal	silver	7440-22-4	0.240	0.24	0.24	2415	2415
solder	non noble metal	tin	7440-31-5	0.017	0.02		172	
	noble metal	silver	7440-22-4	0.021	0.02		215	
	non noble metal	lead	7439-92-1	0.814	0.82	0.86	8195	8582
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003			33	
	non noble metal	iron	7439-89-6	0.011	0.01		109	
	non noble metal	copper	7440-50-8	10.832	10.91	10.92	109056	109198
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.283	0.28	0.28	2848	2852
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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